

Semiconductors

Semiconductors

density of electrons
in the conduction
band

$$n = N_c \left(\frac{T}{300} \right)^{\frac{3}{2}} \exp \left(\frac{\mu - E_c}{k_B T} \right)$$

↑
effective density of
states in the
conduction band at
300 K

density of holes in
the valence band

$$p = N_v \left(\frac{T}{300} \right)^{\frac{3}{2}} \exp \left(\frac{E_v - \mu}{k_B T} \right)$$

↑
effective density of
states in the valence
band at 300 K

The electrical contribution to the thermodynamic properties of insulators depend on band edges

Boltzmann approximation

The table below gives the contribution of electrons in intrinsic semiconductors and insulators to some thermodynamic quantities. These results were calculated in the Boltzmann approximation where it is assumed that the chemical potential lies in the band gap more than $3k_B T$ from the band edge. The electronic contribution to the thermodynamic quantities are usually much smaller than the contribution of the phonons and thus the electronic components are often simply ignored.

	1-d	2-d
Density of states m_e^* and m_h^* are 'density of states' effective masses	$D(E) = \begin{cases} \frac{1}{\hbar\pi} \sqrt{\frac{2m_h^*}{(E_v - E)}} & E < E_v \\ 0 & E_v < E < E_c \\ \frac{1}{\hbar\pi} \sqrt{\frac{2m_e^*}{(E - E_c)}} & E > E_c \end{cases} \quad \text{J}^{-1} \text{m}^{-1}$	$D(E) = \begin{cases} \frac{m_h^*}{\hbar^2\pi} H(E_v - E) & E < E_v \\ 0 & E_v < E < E_c \\ \frac{m_e^*}{\hbar^2\pi} H(E - E_c) & E > E_c \end{cases} \quad \text{J}^{-1} \text{m}^{-2}$ $H(x) = 0 \text{ for } x < 0 \text{ and } H(x) = 1 \text{ for } x > 0$
Density of states N_v and N_c are the effective densities of states	$D(E) = \begin{cases} N_v(300) \sqrt{\frac{2}{300\pi k_B (E_v - E)}} & E < E_v \\ 0 & E_v < E < E_c \\ N_c(300) \sqrt{\frac{2}{300\pi k_B (E - E_c)}} & E > E_c \end{cases} \quad \text{J}^{-1} \text{m}^{-1}$	$D(E) = \begin{cases} \frac{N_v(300)}{300k_B} H(E_v - E) & E < E_v \\ 0 & E_v < E < E_c \\ \frac{N_c(300)}{300k_B} H(E - E_c) & E > E_c \end{cases} \quad \text{J}^{-1} \text{m}^{-2}$
Density of electrons in the conduction band $n = \int_{E_c}^{\infty} D(E) f(E) dE$	$n = \sqrt{\frac{m_e^* k_B T}{\hbar^2 \pi}} \exp\left(\frac{\mu - E_c}{k_B T}\right) \quad \text{m}^{-1}$ $= N_c \exp\left(\frac{\mu - E_c}{k_B T}\right)$	$n = \frac{m_e^* k_B T}{\hbar^2 \pi} \exp\left(\frac{\mu - E_c}{k_B T}\right) \quad \text{m}^{-2}$ $= N_c \exp\left(\frac{\mu - E_c}{k_B T}\right)$
Density of holes in the valence band $p = \int_{-\infty}^{E_v} D(E) (1 - f(E)) dE$	$p = \sqrt{\frac{m_h^* k_B T}{\hbar^2 \pi}} \exp\left(\frac{E_v - \mu}{k_B T}\right) \quad \text{m}^{-1}$ $= N_v \exp\left(\frac{\mu - E_c}{k_B T}\right)$	$p = \frac{m_h^* k_B T}{\hbar^2 \pi} \exp\left(\frac{E_v - \mu}{k_B T}\right) \quad \text{m}^{-2}$ $= N_v \exp\left(\frac{\mu - E_c}{k_B T}\right)$

Intrinsic semiconductors

Near the top of the valence band and the bottom of the conduction band the density of states of a semiconductor can be approximated as,

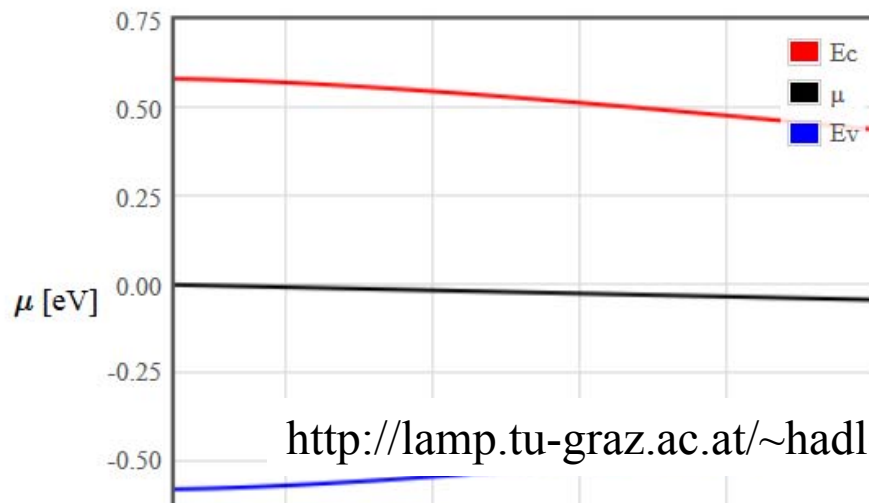
$$D(E) = \begin{cases} D_v \sqrt{E_v - E}, & \text{for } E < E_v \\ 0, & \text{for } E_v < E < E_c \\ D_c \sqrt{E - E_c}, & \text{for } E_c < E \end{cases}$$

Where D_v and D_c are constants that describe the form of the density of states near the band edges. Often in the literature, these constants are given in terms of the 'density of states effective masses' m_h^* and m_e^* or the 'effective density of states at 300 K' $N_v(300)$ and $N_c(300)$. To calculate m_h^* and m_e^* you determine D_v and D_c from a band structure calculation and then calculate the effective mass that would be needed to produce the same density of states from a dispersion relation consisting of a single isotropic parabola $E = \frac{\hbar^2 k^2}{2m^*}$.

$$D_v = \frac{(2m_h^*)^{3/2}}{2\pi^2 \hbar^3} \quad D_c = \frac{(2m_e^*)^{3/2}}{2\pi^2 \hbar^3}$$

In the Boltzmann approximation, the concentration of holes in the valence band p and electrons in the conduction band n are given by,

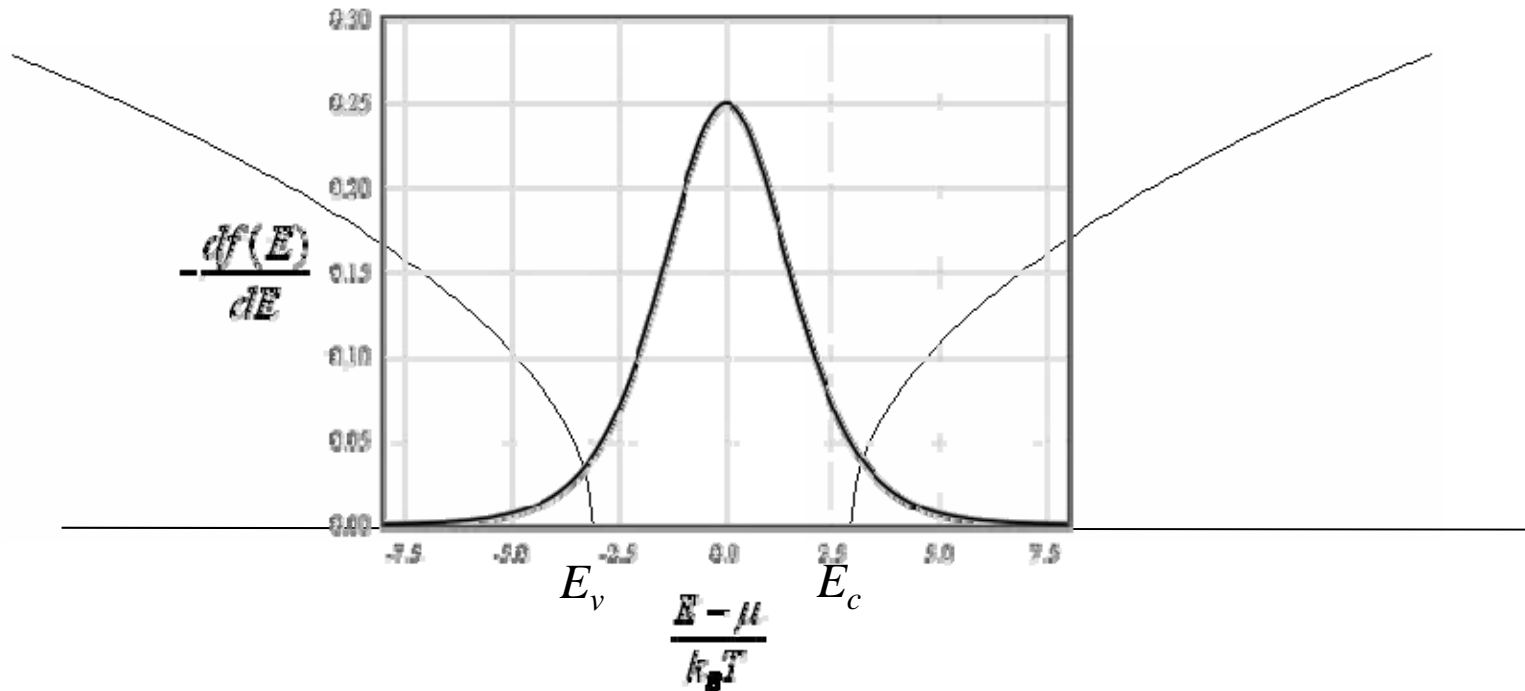
$$p = \frac{2D_v}{\sqrt{\pi}} (k_B T)^{3/2} \exp\left(\frac{E_v - \mu}{k_B T}\right), \quad n = \frac{2D_c}{\sqrt{\pi}} (k_B T)^{3/2} \exp\left(\frac{\mu - E_c}{k_B T}\right).$$



$N_c(300 \text{ K}) =$	<input type="text" value="2.78E19"/>	$1/\text{cm}^3$	Semiconductor <input type="button" value="Si"/> <input type="button" value="Ge"/> <input type="button" value="GaAs"/> <input type="button" value="GaP"/> <input type="button" value="InAs"/> <input type="button" value="InP"/> <input type="button" value="InSb"/>
$N_v(300 \text{ K}) =$	<input type="text" value="9.84E18"/>	$1/\text{cm}^3$	
$E_g =$	<input type="text" value="1.166-4.73E-4*T*T/(T+636)"/>	eV	
$T_1 =$	<input type="text" value="50"/>	K	
$T_2 =$	<input type="text" value="1000"/>	K	

<http://lamp.tu-graz.ac.at/~hadley/ss1/semiconductors/intrinsic.php>

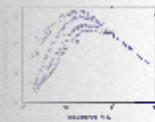
Narrow bandgap semiconductors



Use the programs for metals for small bandgap semiconductors.

Semiconductors

on NSM



Semiconductors

n, k database

InGaAsP

Equivalents

Si	- Silicon	Ge	- Germanium
GaP	- Gallium Phosphide	GaAs	- Gallium Arsenide
InAs	- Indium Arsenide	C	- Diamond
GaSb	- Gallium Antimonide	InSb	- Indium Antimonide
InP	- Indium Phosphide	GaAs_{1-x}Sb_x	- Gallium Arsenide Antimonide
Al_xGa_{1-x}As	- Aluminium Gallium Arsenide		
AlN	- Aluminium Nitride	InN	- Indium Nitride
BN	- Boron Nitride	GaN	- Gallium Nitride

We are going to add new data for:

Ga_xIn_{1-x}As_ySb_{1-y}	- Gallium Indium Arsenide Antimonide	Ga_xIn_{1-x}P	- Gallium Indium Phosphide
Ga_xIn_{1-x}As	- Gallium Indium Arsenide	Ga_xIn_{1-x}Sb	- Gallium Indium Antimonide
InAs_{1-x}Sb_x	- Indium Arsenide Antimonide	Ga_xIn_{1-x}As_yP_{1-y}	- Gallium Indium Arsenide Phosphide
Si_{1-x}Ge_x	- Silicon Germanium	SiC	- Silicon Carbide

Effective Masses

Electrons:

The surfaces of equal energy are ellipsoids.

$$m_l = 0.98m_0$$

$$m_t = 0.19m_0$$

Effective mass of density of states $m_c = 0.36m_0$

There are 6 equivalent valleys in the conduction band.

$$m_{cc} = 0.26m_0$$

Holes:

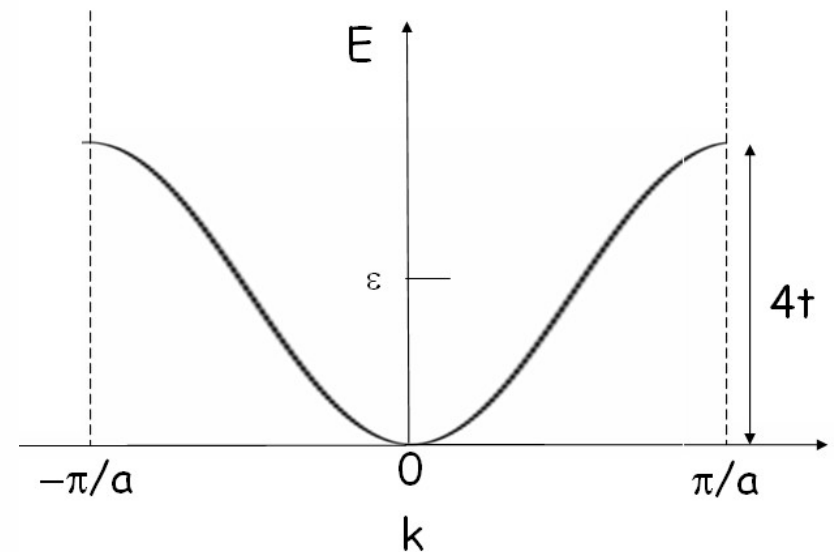
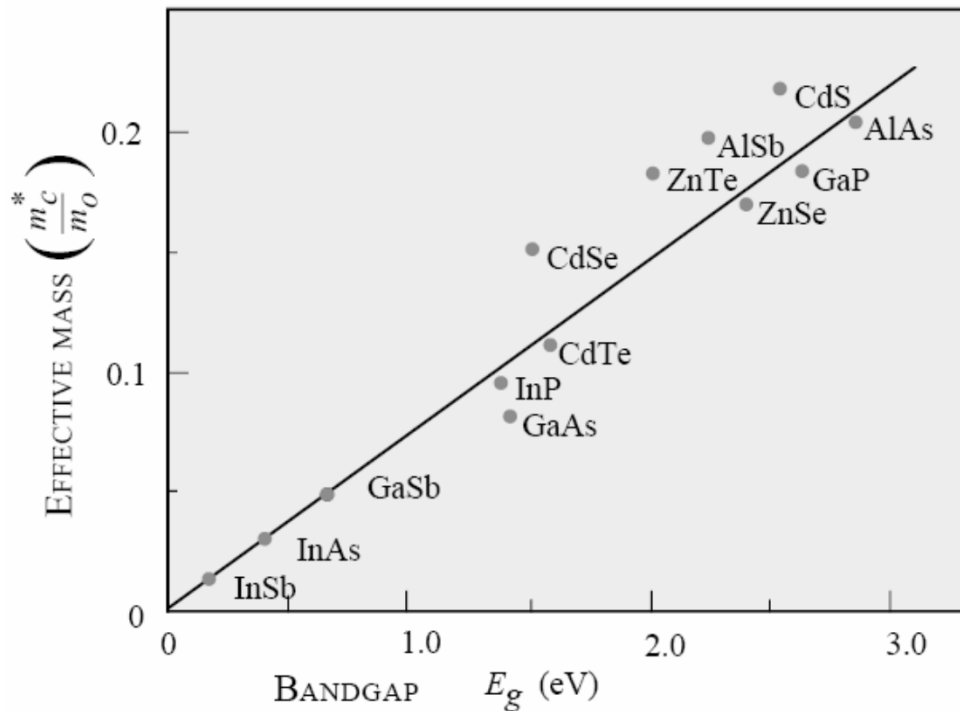
Heavy $m_h = 0.49m_0$

Light $m_{lp} = 0.16m_0$

Split-off band $m_{so} = 0.24m_0$

Effective mass of density of states $m_v = 0.81m_0$

Large gap -> large effective mass



$$E_k = \epsilon - 2t \cos(ka)$$

$$m^* = \frac{\hbar^2}{\frac{d^2 E}{dk^2}}$$

$$\frac{d^2 E}{dk^2} = 2ta^2$$

$$m^* \sim \frac{1}{t}$$

narrow bands -> large effective mass

Measuring the effective mass

Cyclotron resonance $\omega_c = \frac{eB}{m^*}$

Resonant absorption occurs when rf waves with the cyclotron resonance frequency are applied. This can be used to experimentally determine the effective mass.

Knowing the effective mass, the scattering time can be calculated from the measured conductivity.

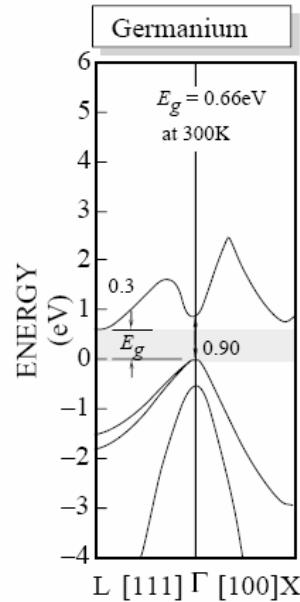
$$\sigma = \frac{ne^2\tau_{sc}}{m^*}$$

Direct and indirect band gaps

indirect bandgap

$$\Delta k \neq 0$$

phonons are emitted



Momentum must be conserved when photons are absorbed or emitted.

direct bandgap:

$$\Delta k = 0$$

photons can be emitted

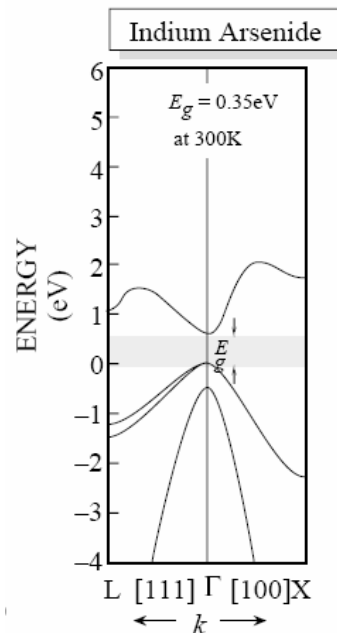
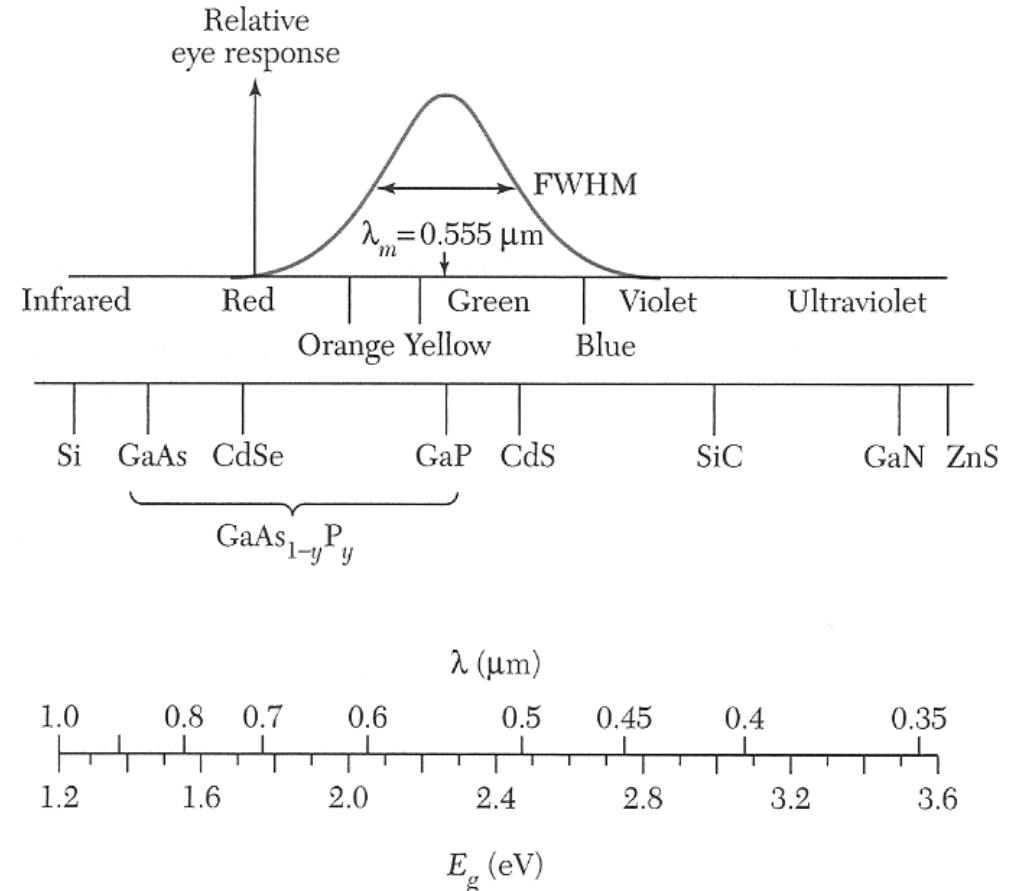


TABLE 1 Common III-V materials used to produce LEDs and their emission wavelengths.

Material	Wavelength (nm)
InAsSbP/InAs	4200
InAs	3800
GaInAsP/GaSb	2000
GaSb	1800
$Ga_xIn_{1-x}As_{1-y}P_y$	1100-1600
$Ga_{0.47}In_{0.53}As$	1550
$Ga_{0.27}In_{0.73}As_{0.63}P_{0.37}$	1300
GaAs:Er, InP:Er	1540
Si:C	1300
GaAs:Yb, InP:Yb	1000
$Al_xGa_{1-x}As:Si$	650-940
GaAs:Si	940
$Al_{0.11}Ga_{0.89}As:Si$	830
$Al_{0.4}Ga_{0.6}As:Si$	650
$GaAs_{0.6}P_{0.4}$	660
$GaAs_{0.4}P_{0.6}$	620
$GaAs_{0.15}P_{0.85}$	590
$(Al_xGa_{1-x})_{0.5}In_{0.5}P$	655
GaP	690
GaP:N	550-570
$Ga_xIn_{1-x}N$	340,430,590
SiC	400-460
BN	260,310,490

Light emitting diodes



Extrinsic semiconductors

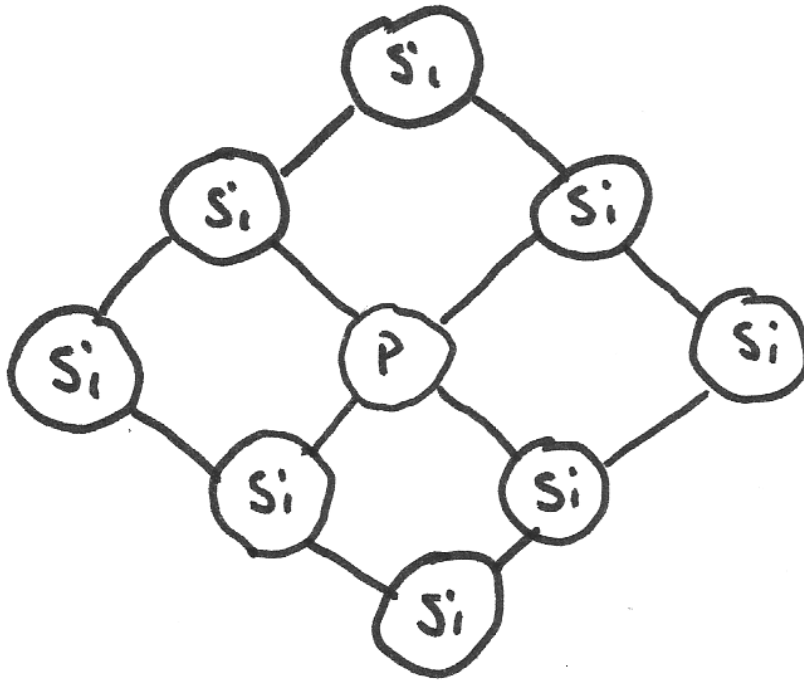
The introduction of impurity atoms that can add electrons or holes is called doping.

n-type : donor atoms contribute electrons to the conduction band.
Examples: P, As in Si.

p-type : acceptor atoms contribute holes to the valence band.
Examples: B, Ga, Al in Si.

	IIIA	IVA	VA	VIA	
	⁵ B	⁶ C	⁷ N	⁸ O	
	¹³ Al	¹⁴ Si	¹⁵ P	¹⁶ S	
IIB	³⁰ Zn	³¹ Ga	³² Ge	³³ As	³⁴ Se
	⁴⁸ Cd	⁴⁹ In	⁵⁰ Sn	⁵¹ Sb	⁵² Te

Ionization of dopants



Easier to ionize a P atom in Si than a free P atom

$$E_n = -\frac{me^4}{8\epsilon_0^2 h^2 n^2}$$

Ionization energy is smaller by a factor: $\frac{m^*}{m} \left(\frac{\epsilon_0}{\epsilon_r \epsilon_0} \right)^2$

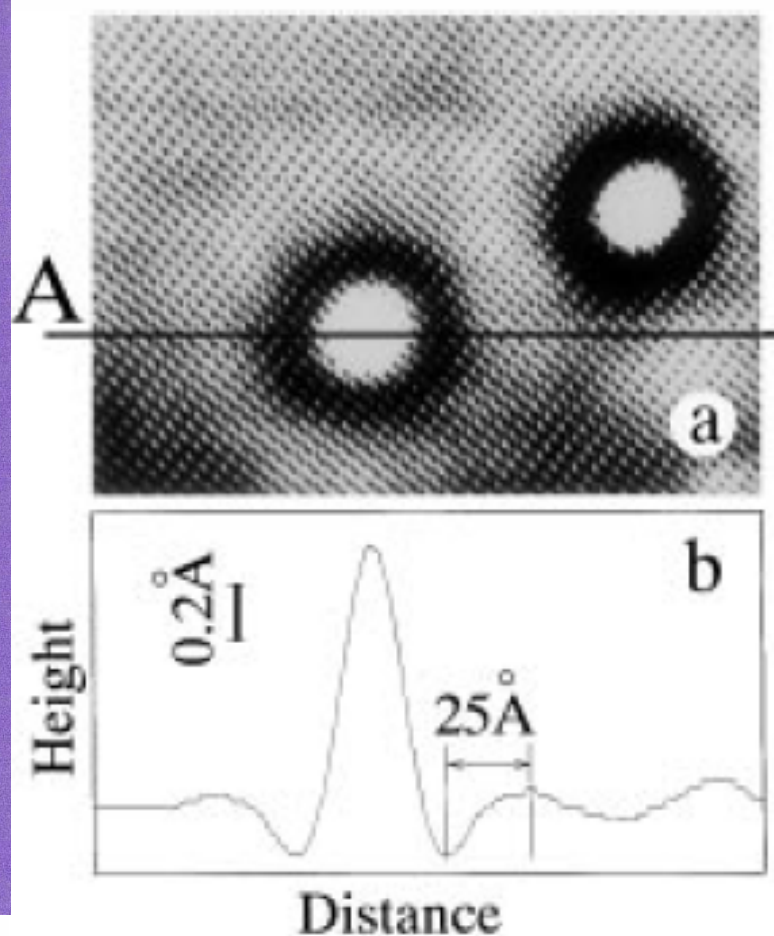
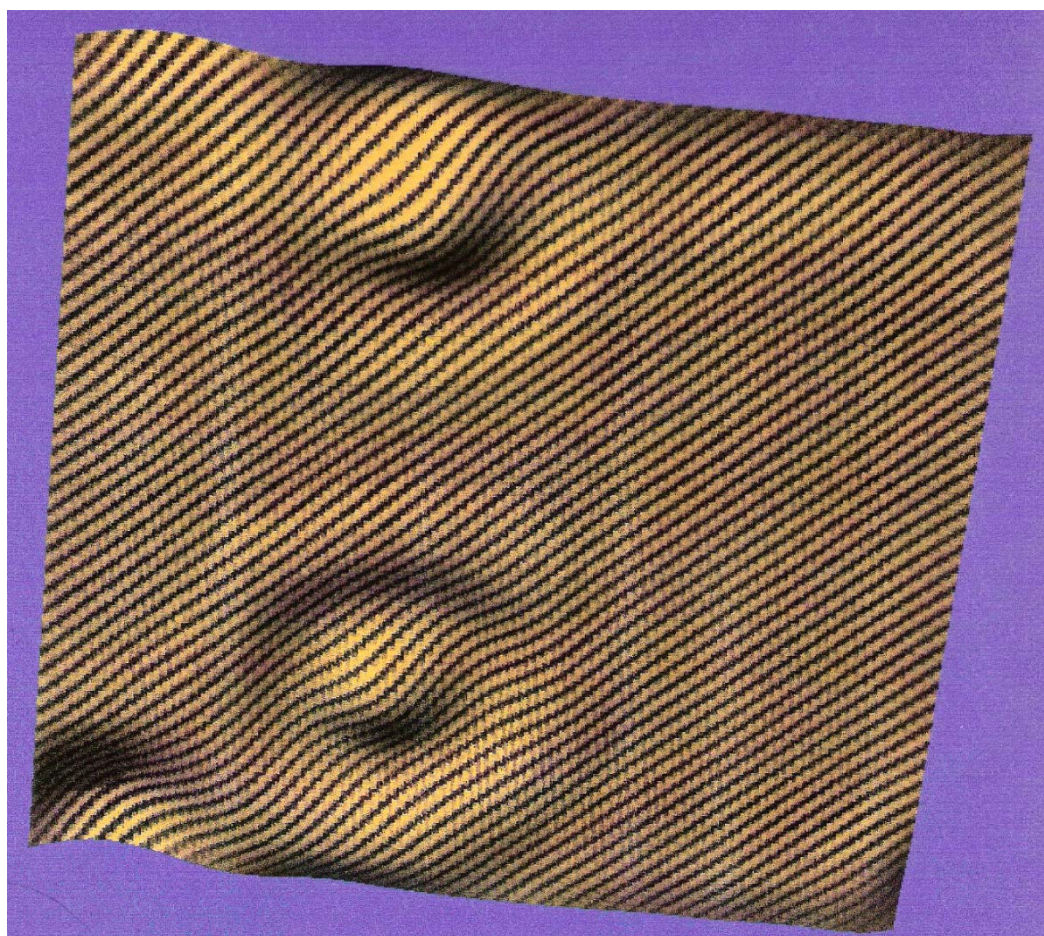
Ionization energy ~ 25 meV

Direct Observation of Friedel Oscillations around Incorporated Si_{Ga} Dopants in GaAs by Low-Temperature Scanning Tunneling Microscopy

M. C. M. M. van der Wielen, A. J. A. van Roij, and H. van Kempen

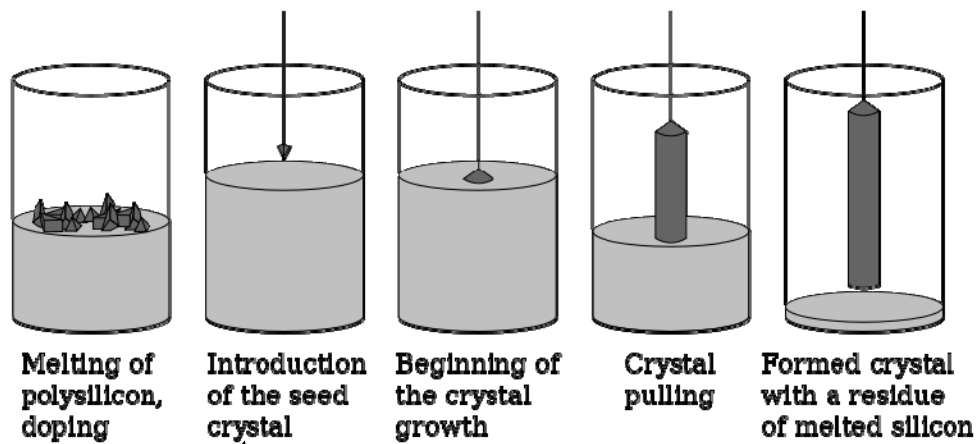
Research Institute for Materials, University of Nijmegen, Toernooiveld 1, 6525 ED Nijmegen, The Netherlands

(Received 25 July 1995)



Crystal growth

Czochralski Process



add dopants to the melt



images from wikipedia

Crystal growth

Float zone Process

Neutron transmutation

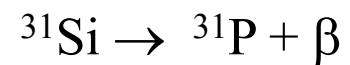
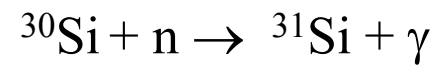
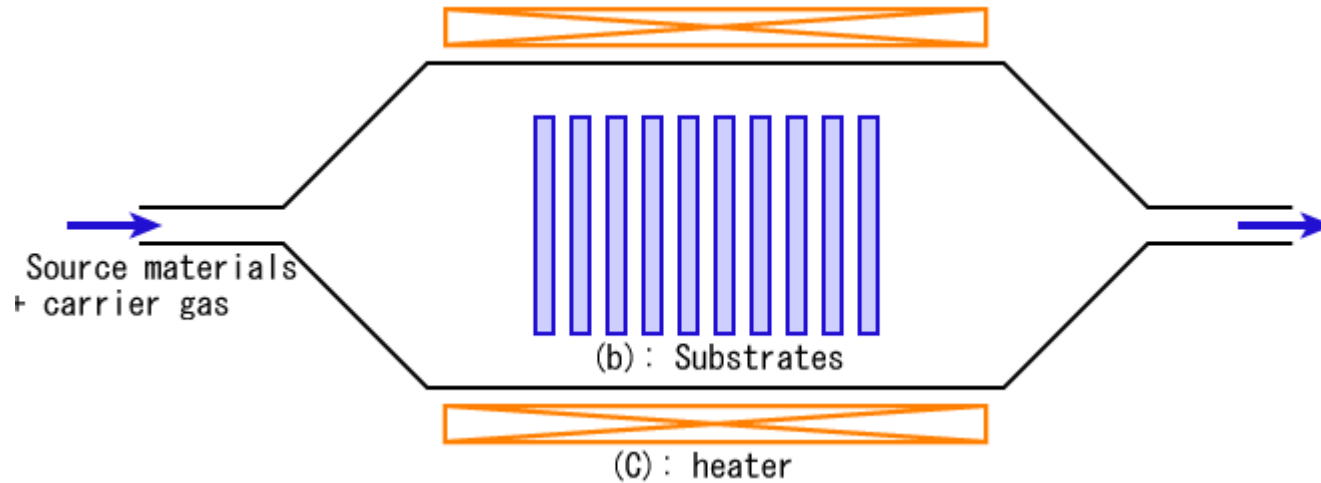


image from wikipedia

Chemical vapor deposition



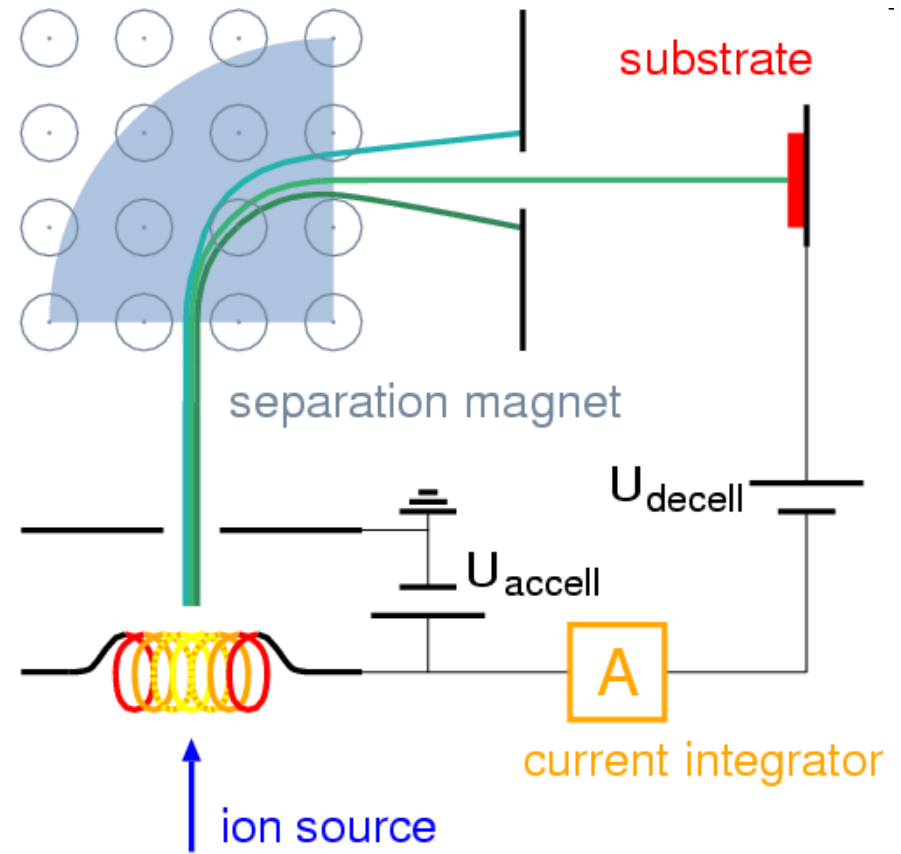
Epitaxial silicon CVD SiH_4 (silane) or SiH_2Cl_2 (dichlorosilane)
 PH_3 (phosphine) for n-doping or B_2H_6 (diborane) for p-doping.

Gas phase diffusion



AsH_3 (Arsine) or PH_3 (phosphine) for n-doping
 B_2H_6 (diborane) for p-doping.

Ion implantation

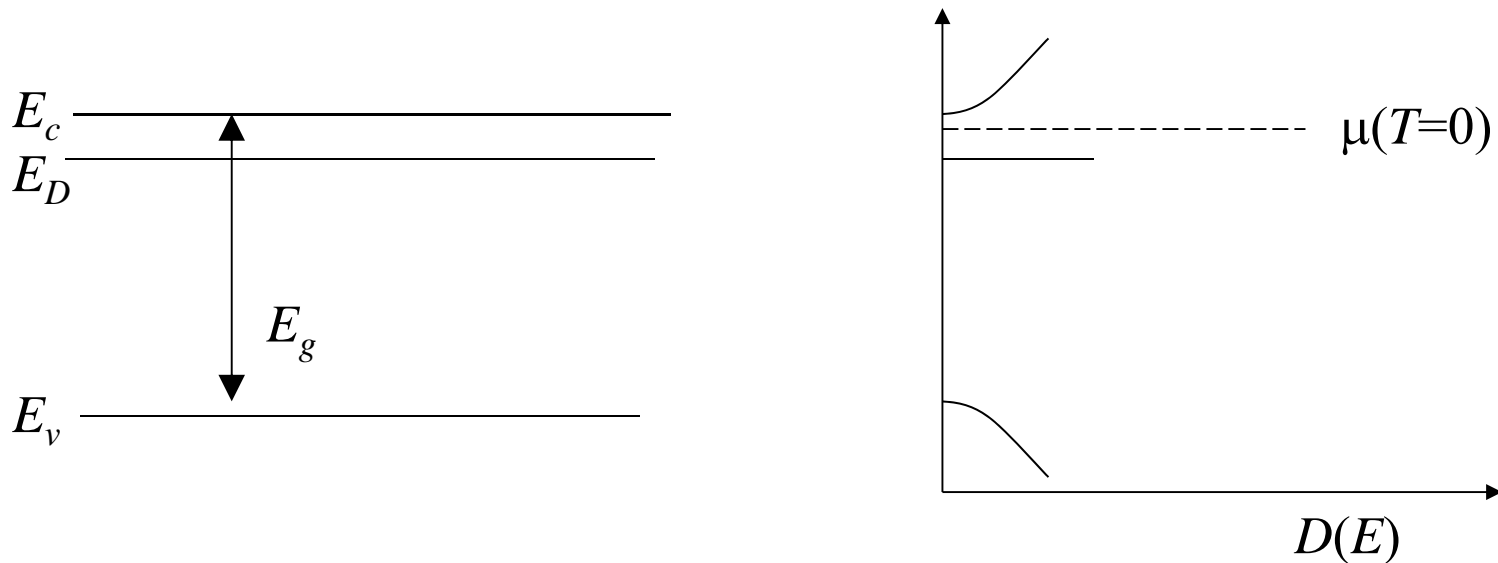


Implant at 7° to avoid channeling

Donors

Five valence electrons: P, As

States are added in the band gap just below the conduction band



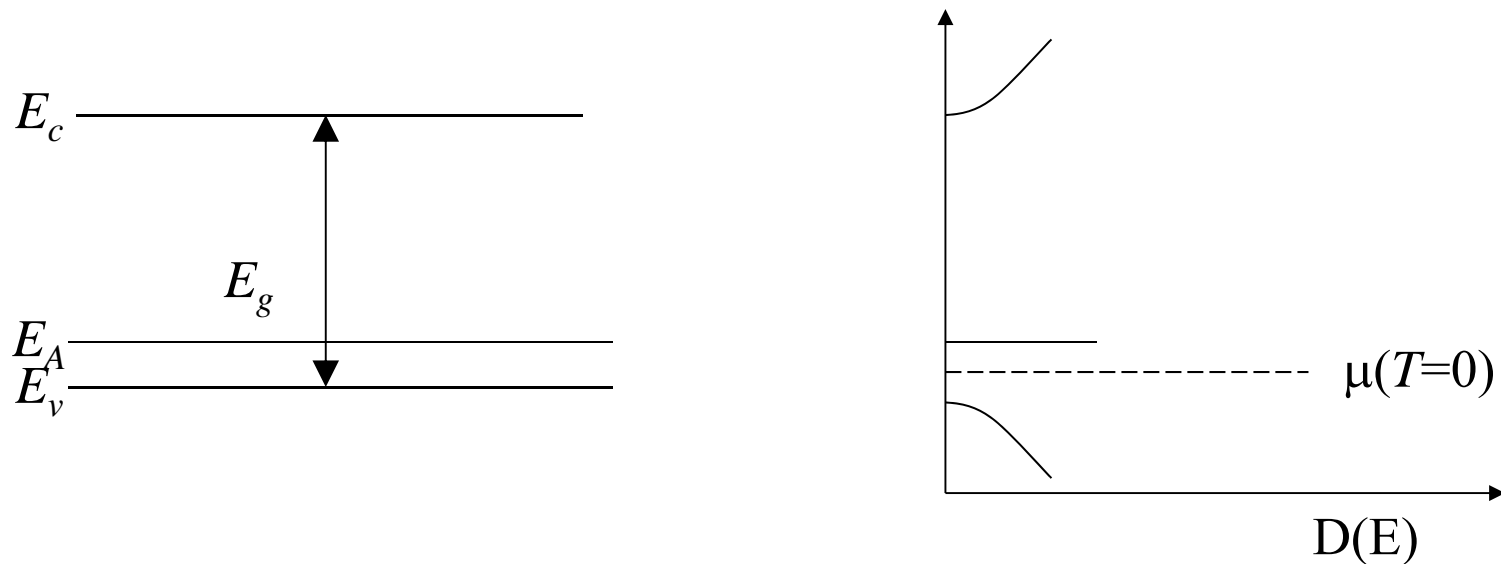
n-type: $n \sim N_D$ Many more electrons in the conduction band than holes in the valence band.

majority carriers: electrons; minority carriers: holes

Acceptors

Three valence electrons: B, Al, Ga

States are added in the band gap just above the valence band



p-type: $p \sim N_A$ Many more holes in the valence band than electrons in the conduction band.

majority carriers: holes; minority carriers: electrons

Donor and Acceptor Energies

Semiconductor	Donor	Energy (meV)
Si	Li	33
	Sb	39
	P	45
	As	54
Ge	Li	9.3
	Sb	9.6
	P	12
	As	13
GaAs	Si	5.8
	Ge	6.0
	S	6.0
	Sn	6.0

Energy below the conduction band



Semiconductor	Acceptor	Energy (meV)
Si	B	45
	Al	67
	Ga	72
	In	160
Ge	B	10
	Al	10
	Ga	11
	In	11
GaAs	C	26
	Be	28
	Mg	28
	Si	35

Energy above the valence band



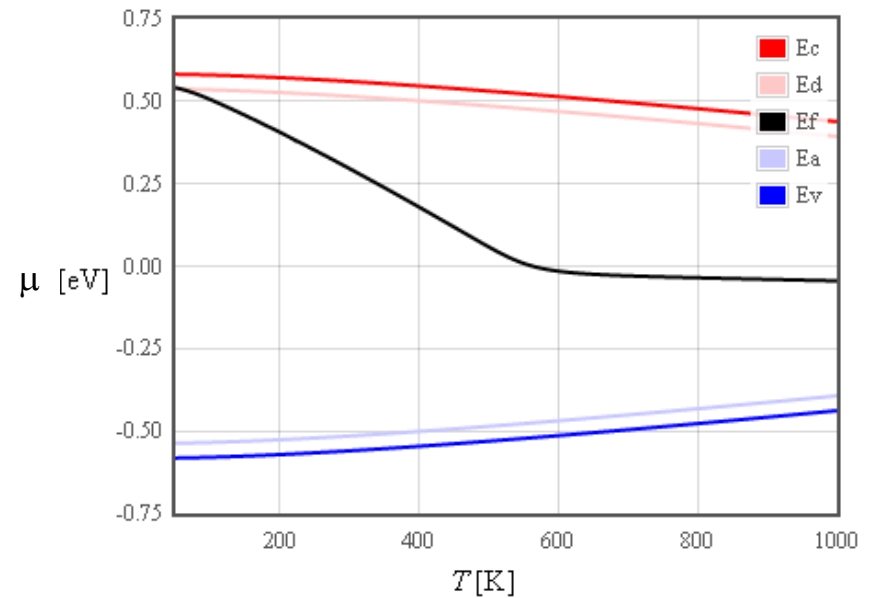
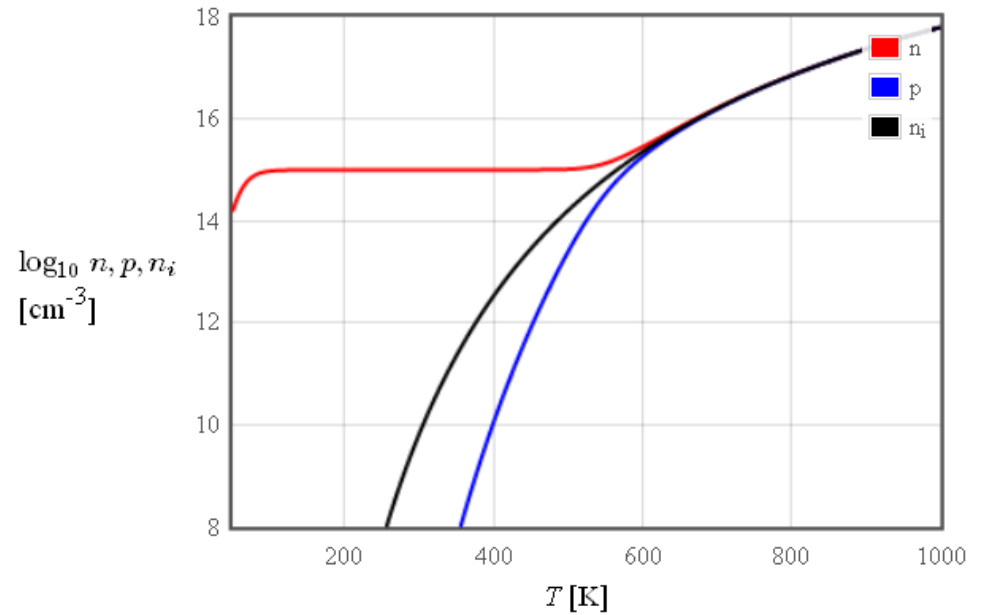
n-type

n-type $N_D > N_A$, $p \sim 0$

$$n = N_D = N_c \exp\left(\frac{\mu - E_c}{k_B T}\right)$$

$$\mu = E_c - k_B T \ln\left(\frac{N_c}{N_D}\right)$$

For n-type, $n \sim$ density of donors,
 $p = n_i^2/n$



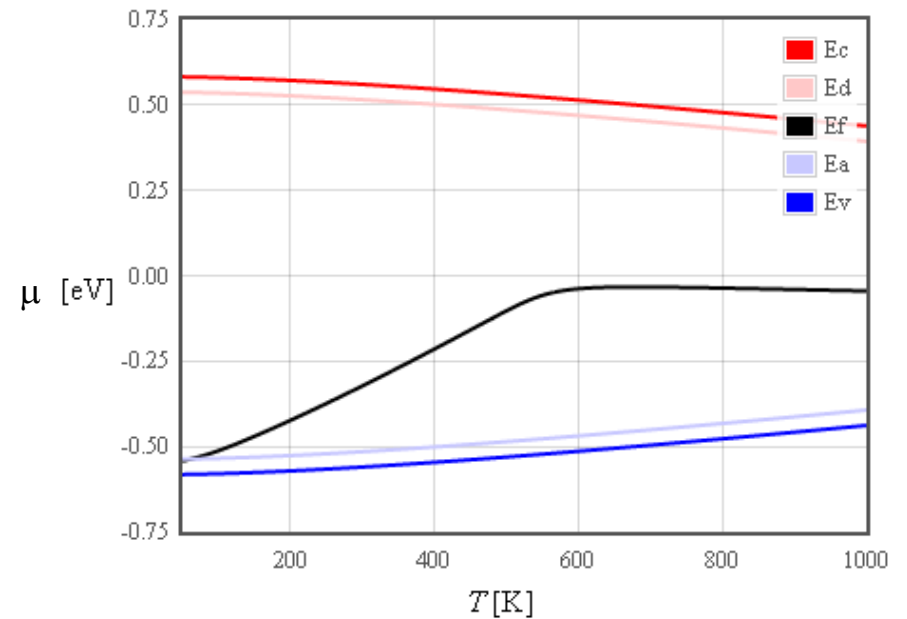
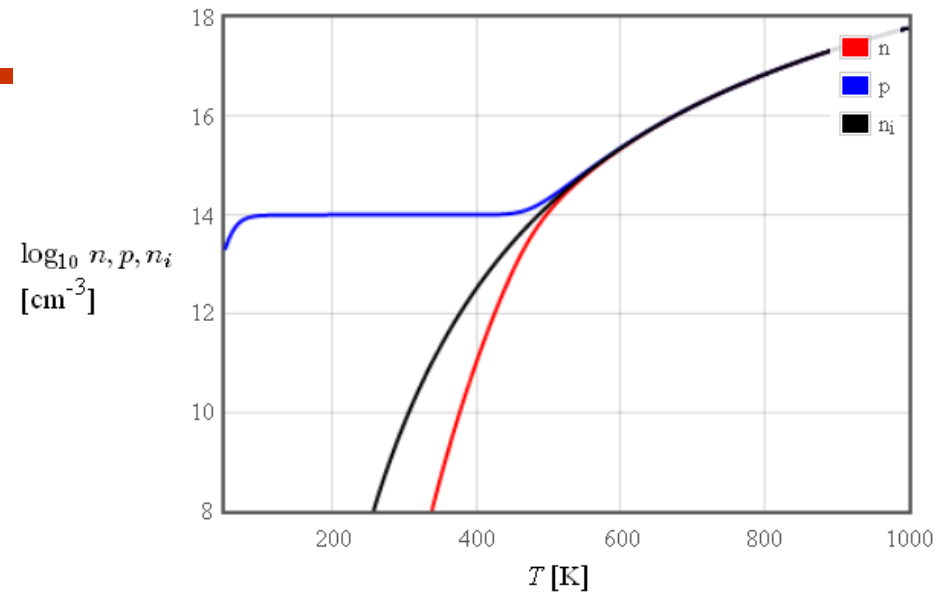
p-type

p-type $N_A > N_D$, $n \sim 0$

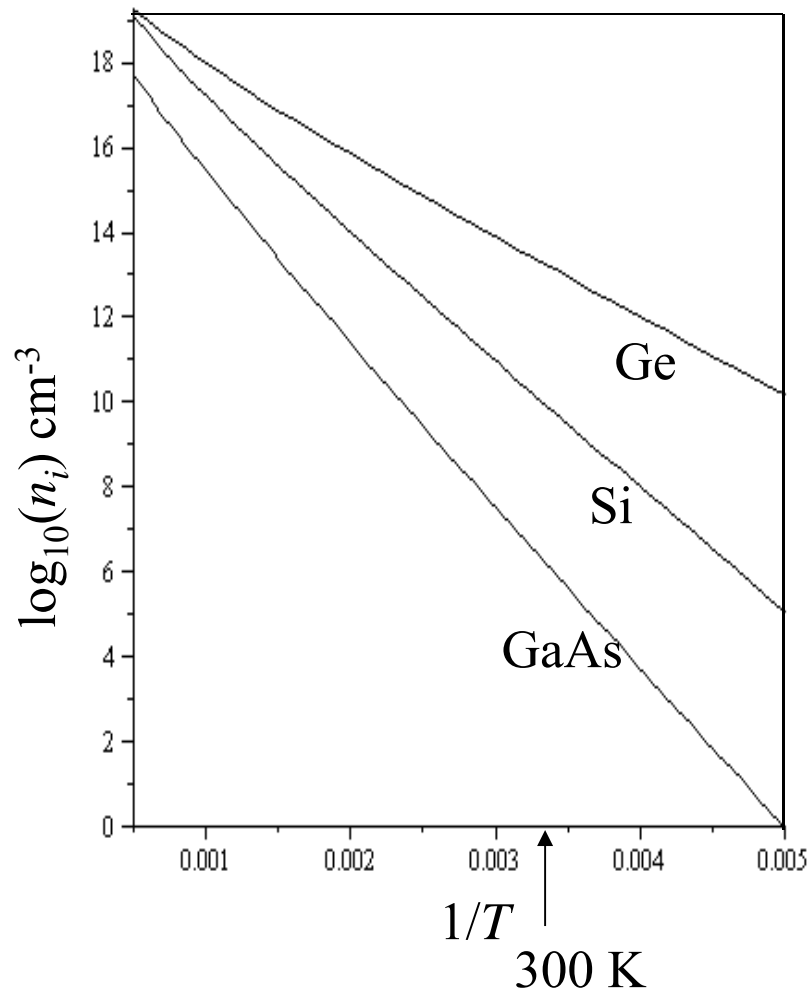
$$p = N_A = N_v \exp\left(\frac{E_v - \mu}{k_B T}\right)$$

$$\mu = E_v + k_B T \ln\left(\frac{N_v}{N_A}\right)$$

For p-type, $p \sim$ density of acceptors,
 $n = n_i^2/p$

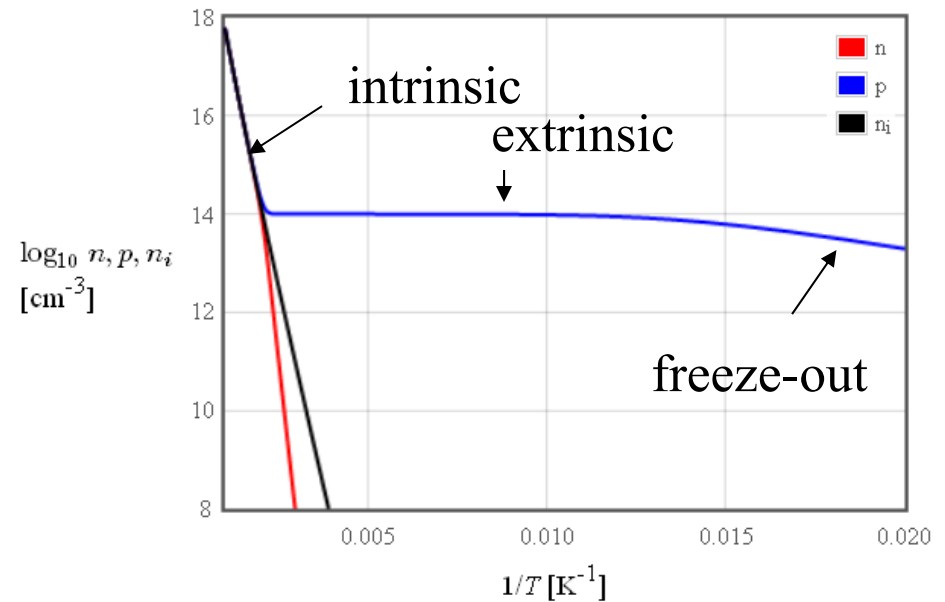


Intrinsic semiconductors



$$n_i = \sqrt{N_v N_c} \exp\left(-\frac{E_g}{2k_B T}\right)$$

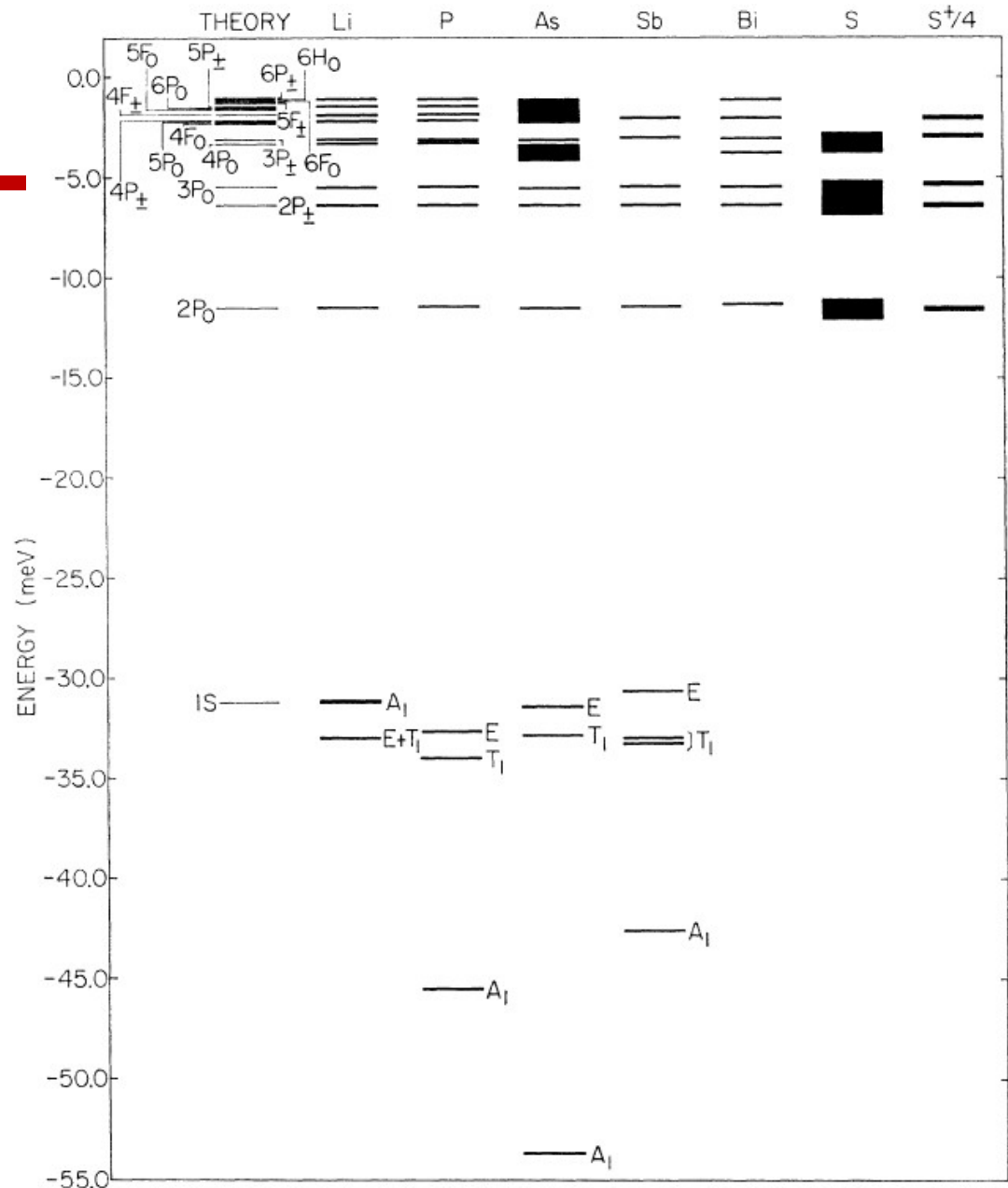
Extrinsic semiconductors



At high temperatures, extrinsic semiconductors have the same temperature dependence as intrinsic semiconductors.

Energy spectra of donors in silicon

FIG. 6. Energy levels of donors in silicon. The theoretical spectrum is based on the dielectric constant appropriate for liquid-helium temperature, $K=11.40$. The experimental spectra have all been arranged so that the $2P_{\pm}$ level in each is lined up with the theoretical $2P_{\pm}$ level. The width of each level represents its experimental uncertainty, with the exception of Bi, for which no experimental error was quoted.



Ionized donors and acceptors

For $E_v + 3k_B T < \mu < E_c - 3k_B T$ Boltzmann approximation

$$N_D^+ = \frac{N_D}{1 + 2 \exp\left(\frac{\mu - E_D}{k_B T}\right)}$$

$$N_A^- = \frac{N_A}{1 + 4 \exp\left(\frac{E_A - \mu}{k_B T}\right)}$$

4 for materials with light
holes and heavy holes (Si)
2 otherwise

N_D = donor density cm^{-3}

N_D^+ = ionized donor density cm^{-3}

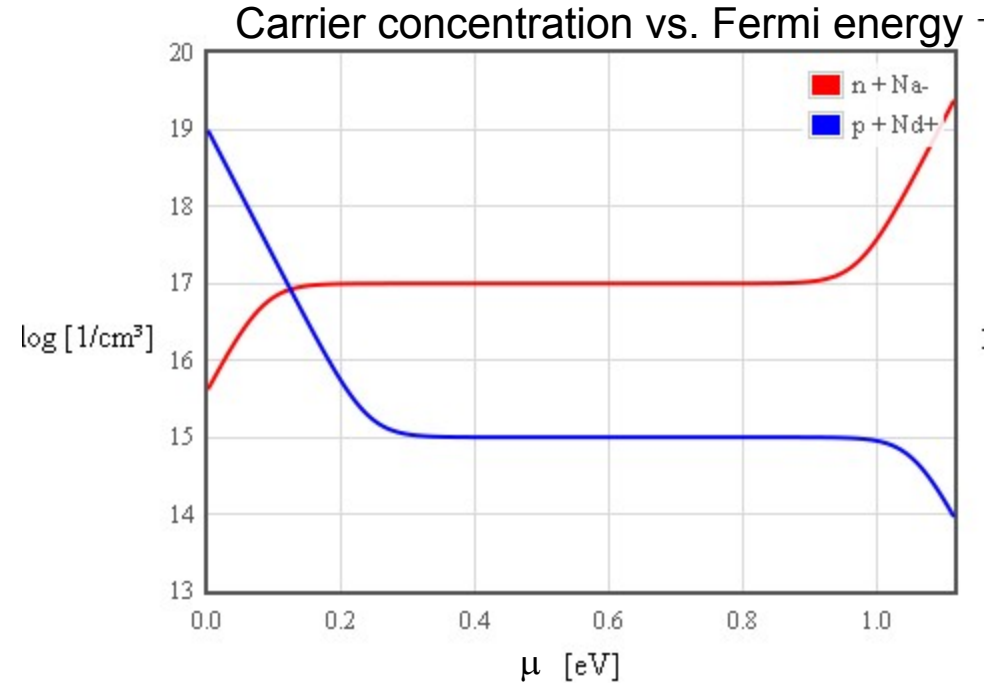
N_A = donor density cm^{-3}

N_A^- = ionized donor density cm^{-3}

Mostly, $N_D^+ = N_D$ and $N_A^- = N_A$

Charge neutrality

$$n + N_A^- = p + N_D^+$$



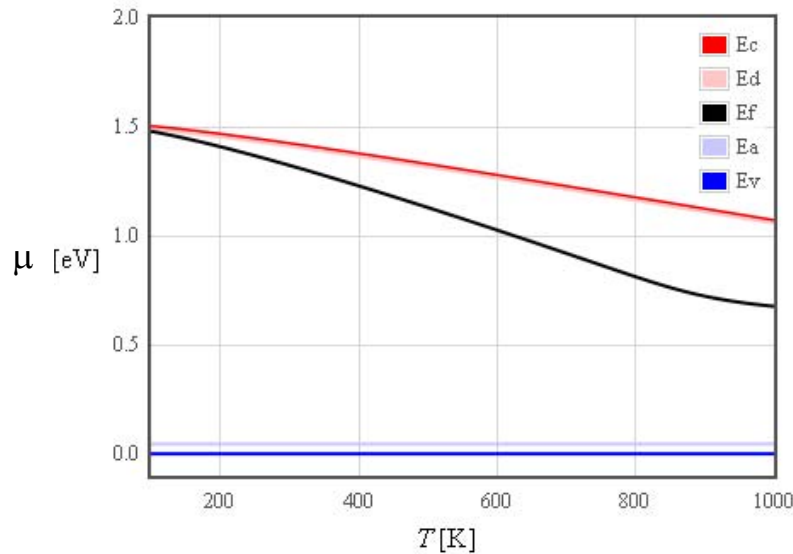
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for ($i=0; $i<500; $i++) {
    $Ef = $i*$Eg/500;
    $n=$Nc*pow($T/300,1.5)*exp(1.6022E-19*($Ef-$Eg)/(1.38E-23*$T));
    $p=$Nv*pow($T/300,1.5)*exp(1.6022E-19*(-$Ef)/(1.38E-23*$T));
    $Namin = $Na/(1+4*exp(1.6022E-19*($Ea-$Ef)/(1.38E-23*$T)));
    $Ndplus = $Nd/(1+2*exp(1.6022E-19*($Ef-$Ed)/(1.38E-23*$T)));
}
    
```

E_f	n	p	N_d^+	N_a^-	$\log(n+N_a^-)$	$\log(p+N_d^+)$
0	4.16629283405	9.84E+18	1E+15	4.19743393218E+15	15.622983869	18.9930392318
0.00224	4.54358211887	9.0229075682E+18	1E+15	4.56020949614E+15	15.6589847946	18.9553946382
0.00448	4.95503779816	8.27366473417E+18	1E+15	4.95271809535E+15	15.694843609	18.9177504064
0.00672	5.40375389699	7.58663741327E+18	1E+15	5.37710747619E+15	15.7305487171	18.8801065693
0.00896	5.89210460791	6.95665026215E+18	1E+15	5.8256000025E+15	15.7660076057	18.8404621605

Fermi energy vs. temperature

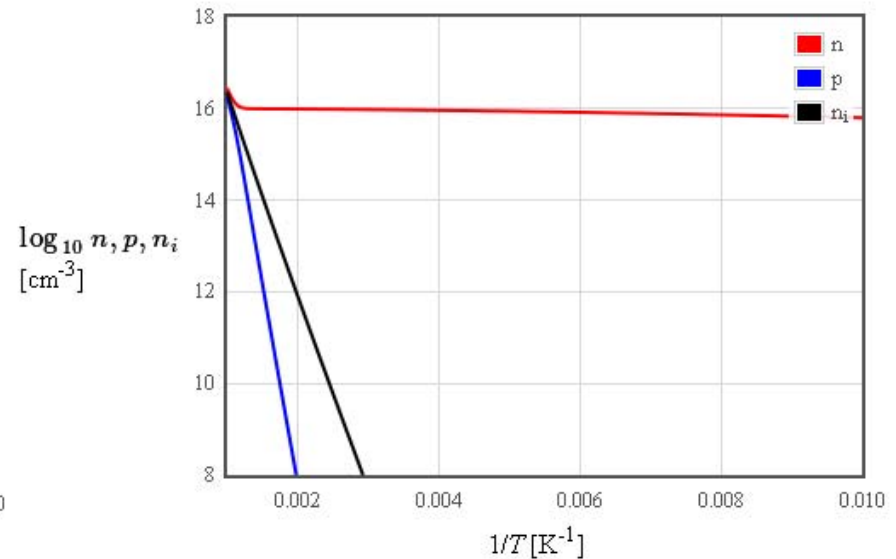
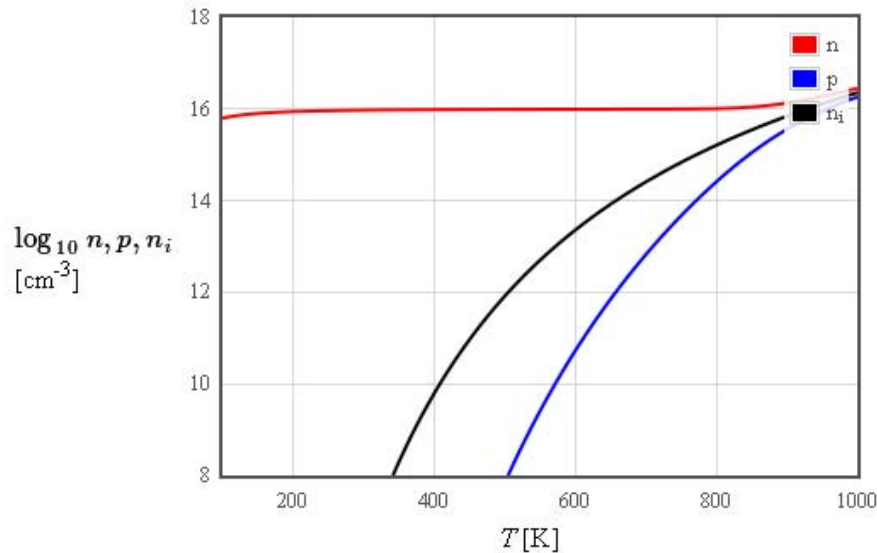
Fermi energy of an extrinsic semiconductor is plotted as a function of temperature. At each temperature the Fermi energy was calculated by requiring that [charge neutrality](#) be satisfied.



$N_c(300\text{ K}) = 4.45\text{E}17$	1/cm ³	Semiconductor	<input type="button" value="Si"/>	<input type="button" value="Ge"/>	<input type="button" value="GaAs"/>
$N_v(300\text{ K}) = 7.72\text{E}18$	1/cm ³		<input type="button" value="P in Si"/>	<input type="button" value="P in Ge"/>	<input type="button" value="Si in GaAs"/>
$E_g = 1.519 - 5.41\text{E-}4 * T * T / (T + 204)$		eV	Donor		
$N_d = 1\text{E}16$	1/cm ³	eV			
$E_c - E_d = 0.012$	eV	Acceptor			
$N_a = 1\text{E}12$	1/cm ³				
$T_1 = 100$	K	<input type="button" value="B in Si"/> <input type="button" value="B in Ge"/> <input type="button" value="Si in GaAs"/>			
$T_2 = 1000$	K				
<input type="button" value="Replot"/>					

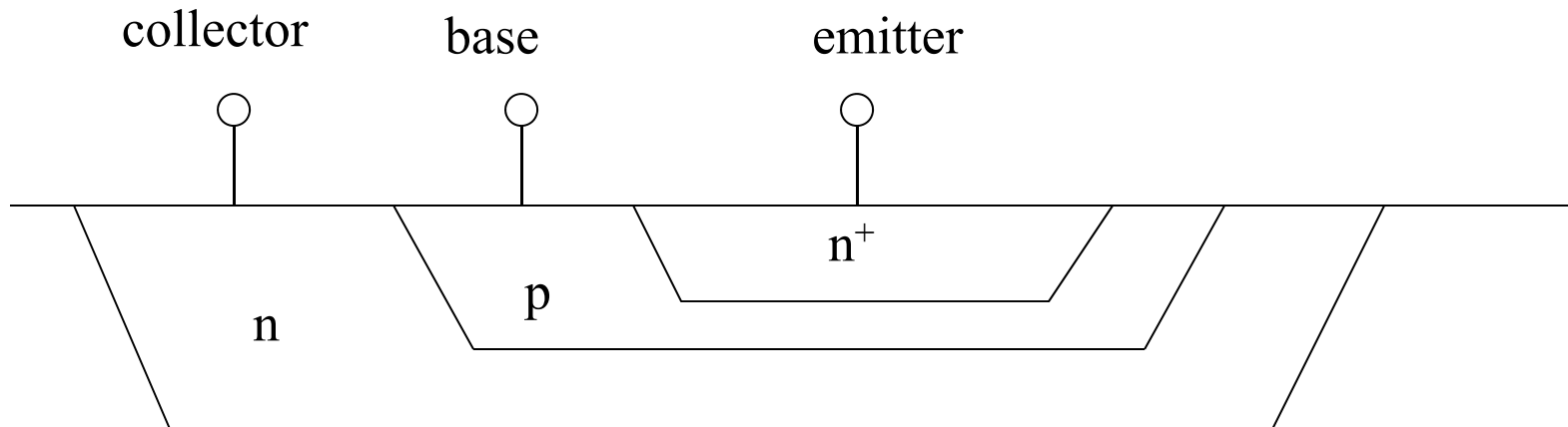
Once the Fermi energy is known, the carrier densities n and p can be calculated from the formulas, $n = N_c \left(\frac{T}{300}\right)^{3/2} \exp\left(\frac{E_F - E_c}{k_B T}\right)$ and $p = N_v \left(\frac{T}{300}\right)^{3/2} \exp\left(\frac{E_v - E_F}{k_B T}\right)$.

The intrinsic carrier density is $n_i = \sqrt{N_c \left(\frac{T}{300}\right)^{3/2} N_v \left(\frac{T}{300}\right)^{3/2} \exp\left(\frac{-E_g}{2k_B T}\right)}$.



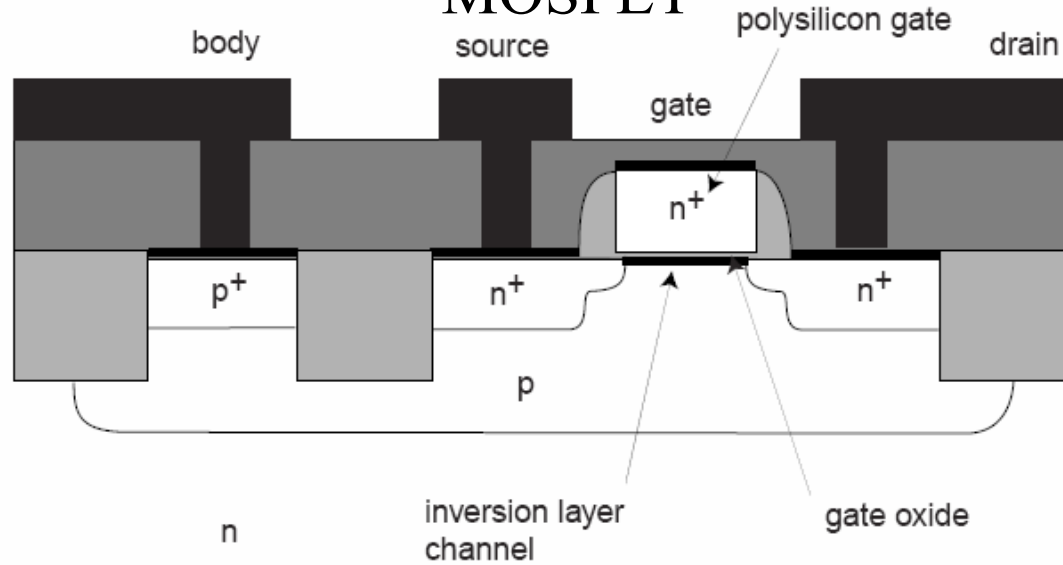
Why dope with donors AND acceptors?

Bipolar transistor

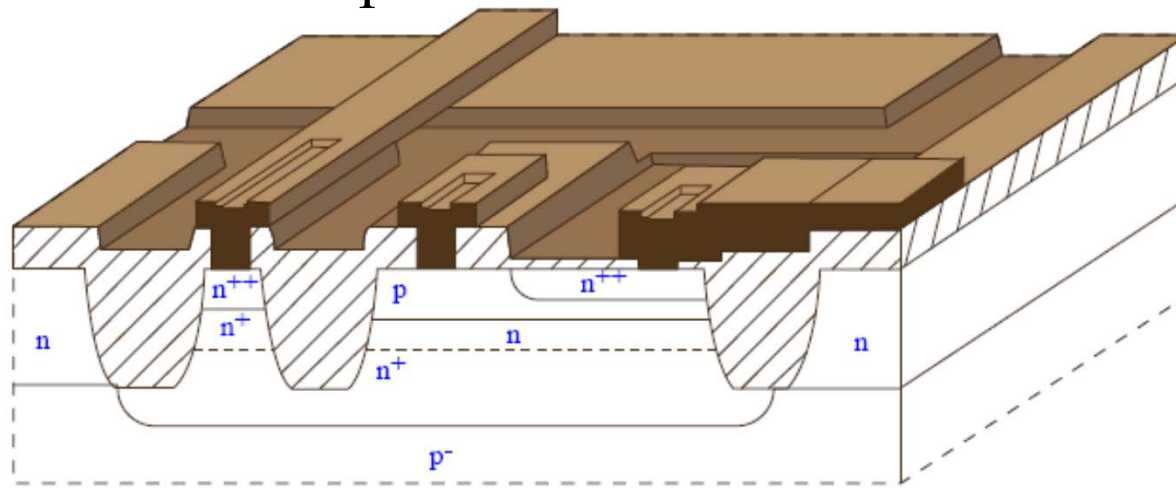


lightly doped p substrate

MOSFET



Bipolar Junction Transistor



Oxide isolated integrated BJT - a modern process